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**YE et al.**(10) **Pub. No.: US 2024/0213271 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **ARRAY SUBSTRATE AND  
MANUFACTURING METHOD THEREOF,  
DISPLAY PANEL AND MANUFACTURING  
METHOD THEREFOR, AND DISPLAY  
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**27/127** (2013.01); **H01L 27/1288** (2013.01)(57) **ABSTRACT**

The present disclosure relates to a manufacturing method for an array substrate, including: forming a first electrode material layer, a conductive enhancement material layer and a protective material layer in sequence, oxidation resistance of the protective material layer being stronger than that of the conductive enhancement material layer; forming a mask pattern on a side of the protective material layer away from the first electrode material layer, the mask pattern including a first portion and a second portion, and a thickness of the first portion being greater than that of the second portion; performing ashing on the mask pattern to remove the second portion to expose the protective material layer covered by the second portion; patterning the first electrode material layer to form a first electrode; and patterning the protective material layer and the conductive enhancement material layer to form a protective layer and a conductive enhancement layer.

